



SOT2114-2

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

9 April 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN68
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-07-2020
Manufacturer package code	98ASA01671D

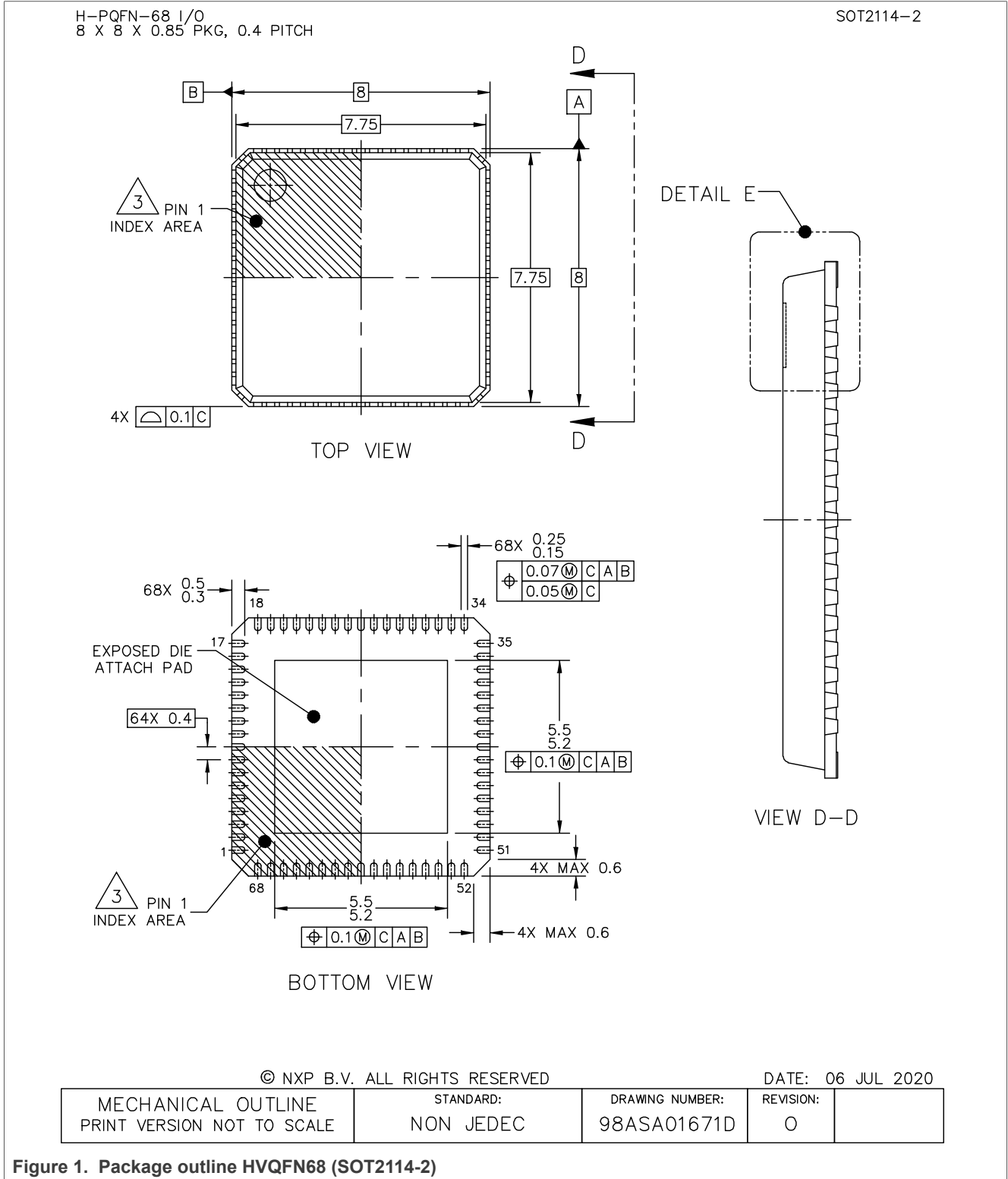
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	68	-	



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2 Package outline



HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

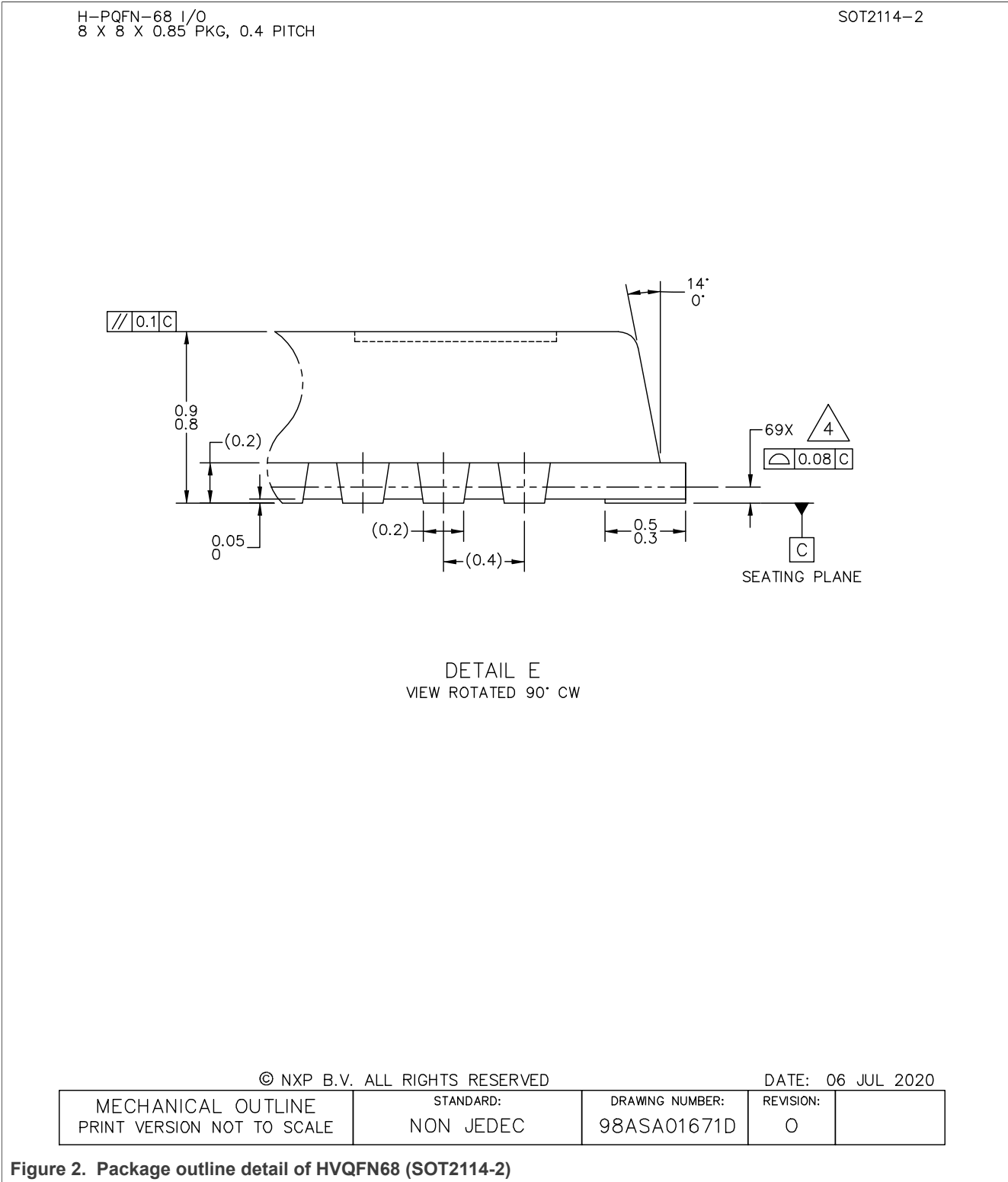
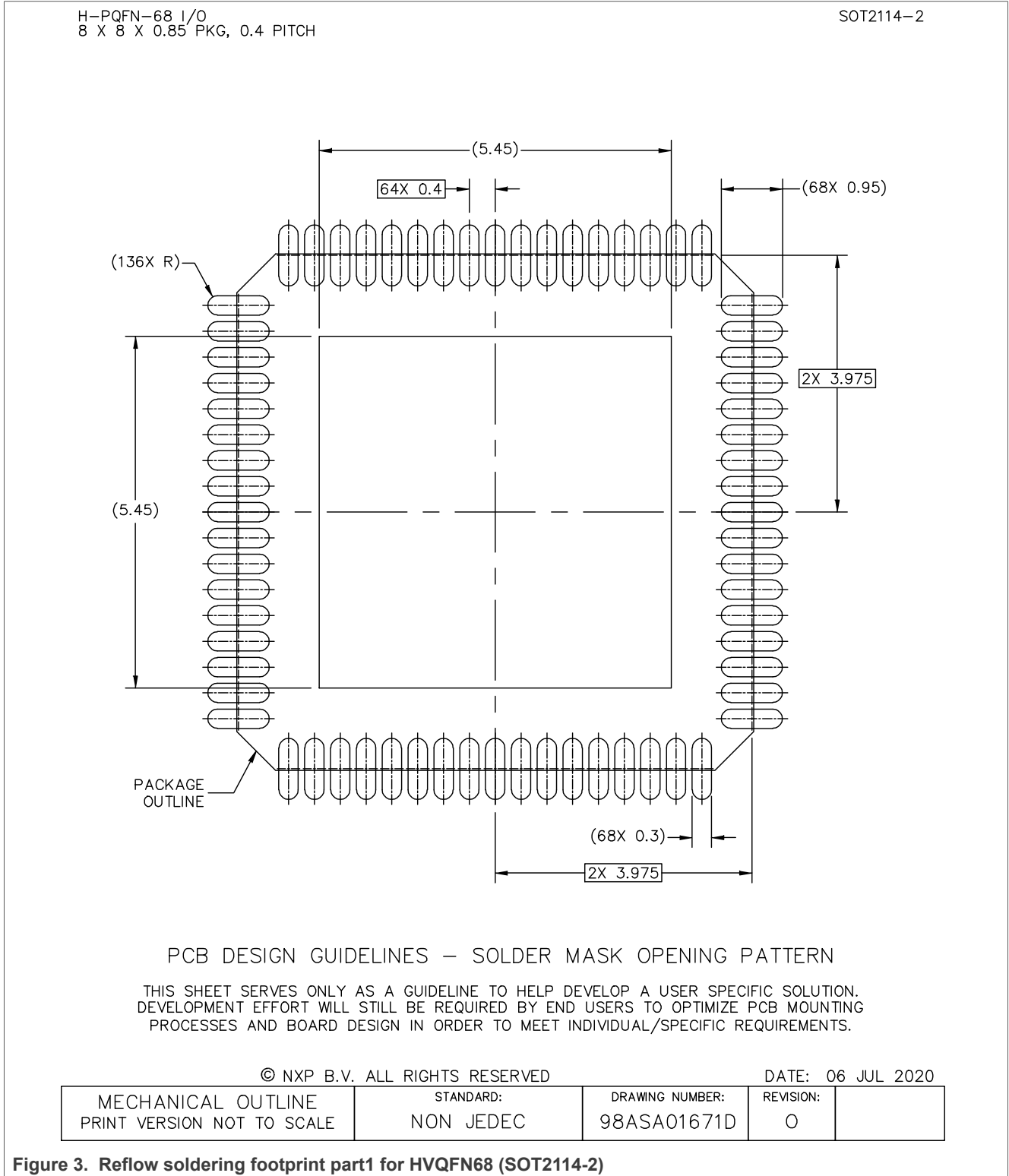


Figure 2. Package outline detail of HVQFN68 (SOT2114-2)

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3 Soldering



HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

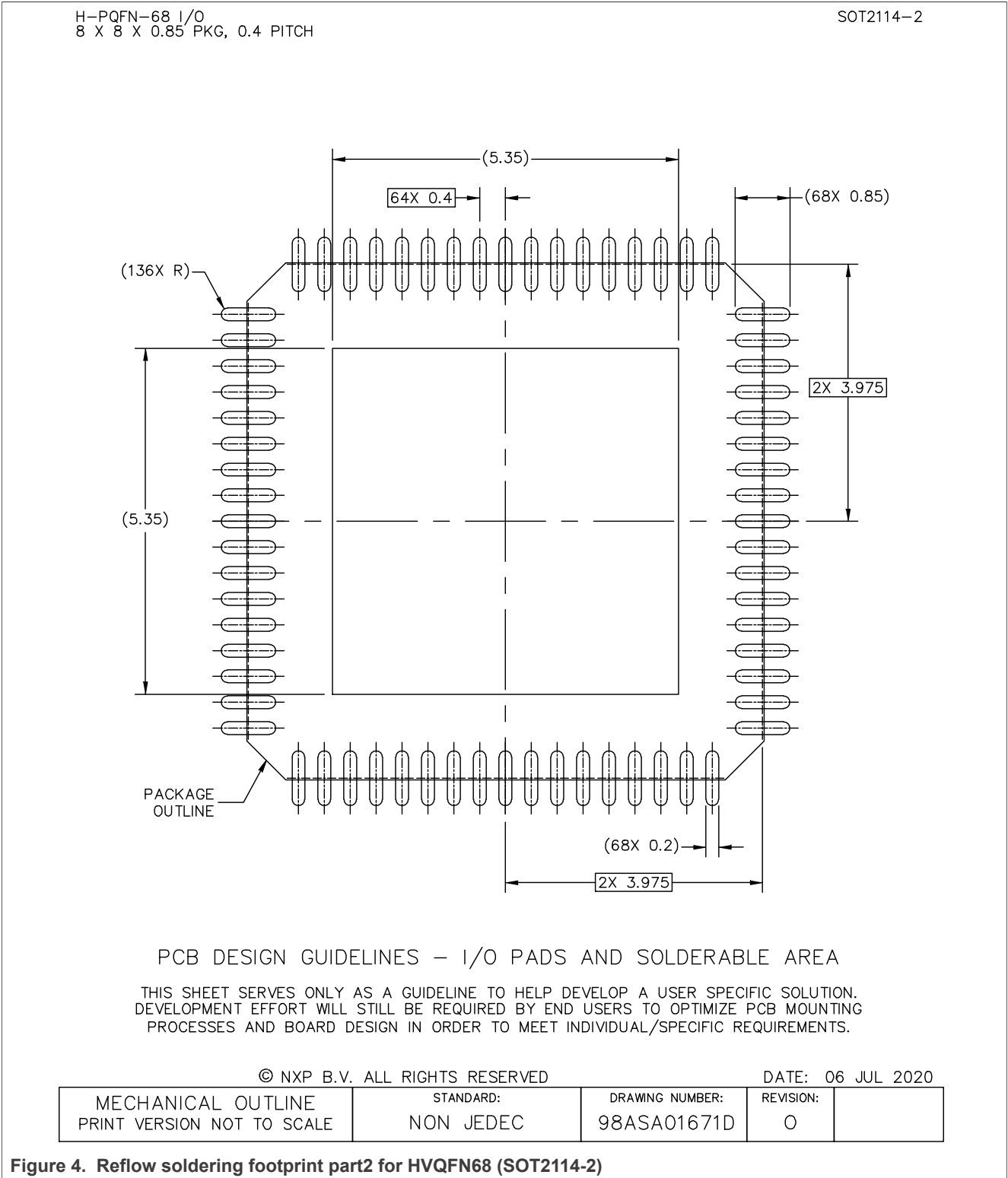


Figure 4. Reflow soldering footprint part2 for HVQFN68 (SOT2114-2)

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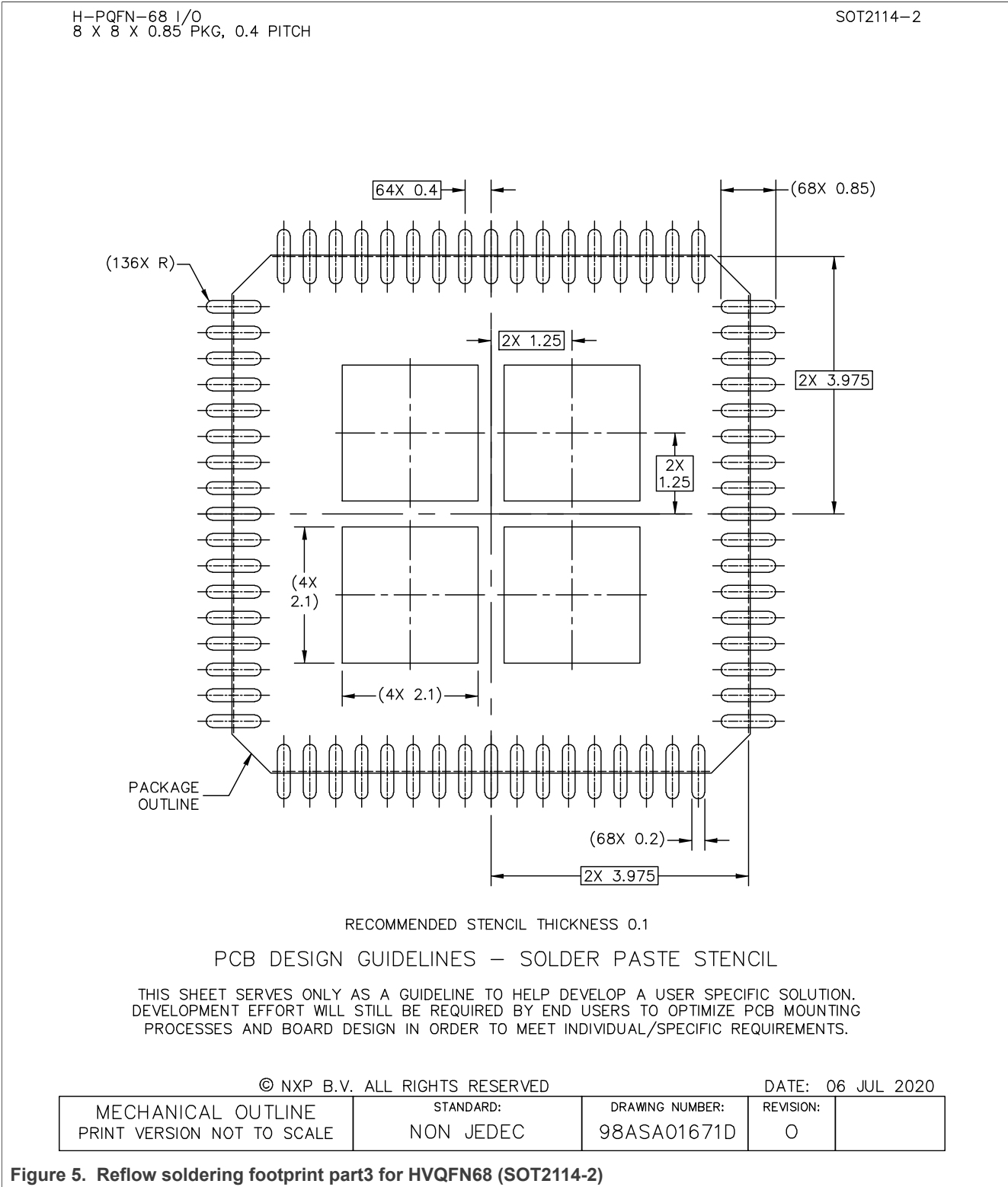


Figure 5. Reflow soldering footprint part3 for HVQFN68 (SOT2114-2)

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

H-PQFN-68 I/O
8 X 8 X 0.85 PKG, 0.4 PITCH

SOT2114-2

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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DATE: 06 JUL 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01671D	REVISION: 0
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Figure 6. Package outline note HVQFN68 (SOT2114-2)

4 Legal information

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